

Day 1 - Monday 15th April 2024

18:30 Pre-conference networking drinks reception

Day 2 - Tuesday 16th April 2024

08:00 Registration and welcome refreshments

09:10 Housekeeping by Rob Harper - Conference Chair for the morning session

Technology Developments in WBG: SiC, GaN and Beyond

Sponsored by SCREEN Semiconductor Solutions Co., Ltd.

09:20 Aluminum Scandium Nitride (AlScN) a novel material for power electronic applications

Presented by Ali Yassine - University Freiburg

09:40 Facing SiC Challenges Thanks to UV Laser Annealing Products from SCREEN

Presented by Louis Thuries - SCREEN SPE

10:00 Cost-effective SiC substrate manufacturing for power devices enabled by oxide-free wafer bonding

Presented by Dr. Bernd Dielacher - EV Group

10:20 Morning Break

11:00 SuperGaN's Performance Advantages Challenging SiC's Long-Term Use

Presented by Philip Zuk - Transphorm

11:20 Exploring WBG's technical advances with a glimpse into next UWBG

Presented by Taha Ayari - Yole Group

11:40 Electronic Packaging Materials for SiC Power Modules

Presented by Dr. Michael Joerger - Heraeus Electronics

12:00 Gallium Oxide – Taking over from SiC?

Presented by Martin Kuball - University of Bristol

12:20 Lunch Break

13:35 Ezgi Dogmus - Conference Chair for afternoon session

13:35 PowerElec – new metrological tools for quality control of wide bandgap semiconductors

Presented by Sebastian Wood - NPL

13:55 Novel interconnect and packaging technologies for power module manufacturing

Presented by Huub Claassen - Boschman Advanced Packaging Technology

14:15 SiC technology optimisation using advanced modelling tools

Presented by Ahmed Nejim - Silvaco

14:35 Advanced Lapping and polishing processes for SiC Wafers for sustainable and cost effective wafers

Presented by Dr. Ravi Bollina - Pureon AG

14:55 Afternoon Break

Silicon MOSFETs and IGBTs: Evolving for the Future

15:35 High voltage power switch: continuous silicon development as contributor to the green transition

Presented by Antonino Gaito - STMicroelectronics

15:55 Future developments within IGBTs, and how they may coexist with SiC

Presented by Callum Middleton - Omdia

16:15 Closing Remarks

16:20 Networking Drinks / Dinner Reception

Day 3 - Wednesday 17th April 2024

08:00 Registration and welcome refreshments

09:10 Housekeeping by Denis Marcon - Conference Chair for morning session

System Reliability - Testing Times

09:20 **SCREEN's Sustainable Cost-of-Ownership (CoO) Portfolio for Thickness Measurement and Wafer Inspection in Power Devices, Automotive, and IoT Applications**

Presented by Alessandro Rossi - SCREEN SPE

09:40 **Enabling Test Automation in Power Electronics Reliability**

Presented by Andrea Vinci - Tektronix

10:00 **How to Correctly Select a High Definition Oscilloscope and Probe for SiC and GaN Power Device Measurement Accuracy**

Presented by Maurizio Mastrofini - Teledyne LeCroy

Capacity Across the Supply Chain

10:20 **The Power Play : Unveiling Capacity Challenges in SiC and GaN Industries**

Presented by Ezgi Dogmus - Yole Group

10:40 Morning Break

GaN - Widening the Application Space

11:20 **How to unleash the power savings of GaN in high power, high voltage applications**

Presented by Rupert Baines - QPT

11:40 **New Opportunities for Gallium Nitride in Power, Sensing and RF**

Presented by Rob Harper - Compound Semiconductor Centre

12:00 **Activating GaN's Full Potential with Digital Control for Enhanced Performance Across All Electronics Sectors**

Presented by Thierry Bouchet - Wise Integration

12:20 **Price competitive GaN power devices to enhance performances, shrinking size and lowering cost of power conversion solutions**

Presented by Denis Marcon - Innoscience Europe BV

12:40 **GaN is widening the applications field in power electronics**

Presented by Eric Moreau - STMicroelectronics

13:00 **Bi-directional circuits open up new opportunities in off-grid applications**

Presented by Alfred Hesener - Navitas

13:20 Lunch Break

Upgrading the GRID – The Role of Power Electronics (inc. Energy Waste and Efficiency)

14:35 **Peter Friedrichs - Conference Chair for afternoon session**

14:35 **High-Voltage Silicon Carbide Enables an Omnidirectional Grid**

Presented by Kevin Speer - Microchip

14:55 **The grid of the future and how SiC power devices will enable the transition towards zero CO2**

Presented by Peter Friedrichs - Infineon

15:15 **3.3 kV SiC MOSFETs Accelerate Grid-Connected Energy Storage**

Presented by Ranbir Singh - Navitas

15:35 **Closing Remarks**



NOTES

This image shows a single sheet of white paper with horizontal ruling lines. The lines are evenly spaced and run across the width of the page. There are no margins, text, or other markings on the paper.